ABSOCIATION CONNECTING LECTRONICS INDUSTRIES® INDUSTRIES®	burn, Illinois, Al	ll rights reserved utions.	under both	This docume level parts, t	ent is a declaration entities of the declaration entities	on of the su	bstances v s all lower	vithin the manufactur level materials for wh	er listed ite hich the m	em. Note: i anufacture	if the item is an as r has engineering	sembly with lower responsibility.	
IPC Web Site for Information on http://www.ipc.org/IPC-175x	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information								
Supplier Information													
Company name*	apany name* Company unique ID			Unique ID Authority					Response Date*				
onsemi									2024-05-08				
Contact Name	Title - Contact]	Phone - Contact*				Email - Contact*				
Product-Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorized Representative*	rized Representative* Title - Representative]	Phone - Representative*				Email - Representative*				
Product-Env-Stewards Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com				
Requester Item Number Mfr Iter	n Number	Mfr Item Name			Effective Date Version		М	Manufacturing Site		/eight*	UOM	Unit Type	
NRVHI 3G	VHP420MFDWFT 200V/2A PUF DF1		FN-8		2024-05-08		М	MY1		9.49	mg	Each	
Manufacturing Proccess Information													
Terminal Plating / Grid Array Material	Terminal Base A	J-STD-020 MSI	L Rating	Peak Process Body Temperature Max			e Max Time at Peak	Temperatu	re Numb	ber of Reflow Cyc	les		
Matte Tin (Sn) - annealed	Matte Tin (Sn) - annealed CU Alloy		1		260		С	30	second	s 3			
Comments													
level 1 - maximum time at peak temperature during so	oldering is 10-30) seconds											
For more information regarding material composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et					
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of				
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted				
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the				
Supplier Digital Signature	astislav Drska	Le							

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	0.34	mg	Supplier	Zinc (Zn)	7440-66-6		0.0004	mg
			Supplier	Iron (Fe)	7439-89-6		0.008	mg
			Supplier	Copper (Cu)	7440-50-8		0.3315	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0001	mg
Die	0.36	mg	Supplier	Silicon (Si)	7440-21-3		0.36	mg
Die Attach Solder	0.82	mg	Supplier	Silver (Ag)	7440-22-4		0.0205	mg
			А	Lead (Pb)	7439-92-1	7a	0.7585	mg
			Supplier	Tin (Sn)	7440-31-5		0.041	mg
Lead Frame	37.39	mg	Supplier	Silver (Ag)	7440-22-4		0.3739	mg
			Supplier	Iron (Fe)	7439-89-6		0.0374	mg
			Supplier	Copper (Cu)	7440-50-8		36.9675	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0112	mg
Mold Compound-Black	48.93	mg		Epoxy resin	proprietary data		3.6698	mg
			Supplier	Phenolic Resin	Proprietary Data		1.2233	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		3.6698	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2446	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		40.1226	mg
Plating	1.56	mg	Supplier	Tin (Sn)	7440-31-5		1.56	mg
Wire Bond - Cu	0.09	mg	Supplier	Copper (Cu)	7440-50-8		0.09	mg